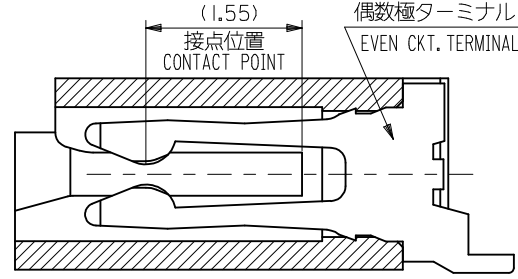


SECT. M-M

SCALE 20:1



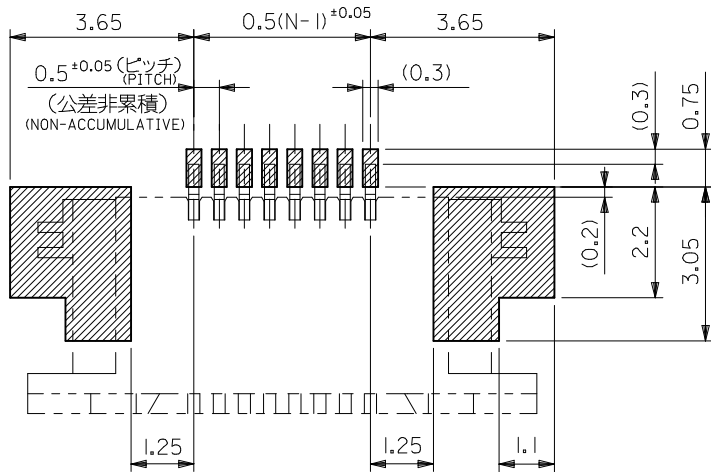
SECT. F-F

SCALE 20:1

注記(NOTES)

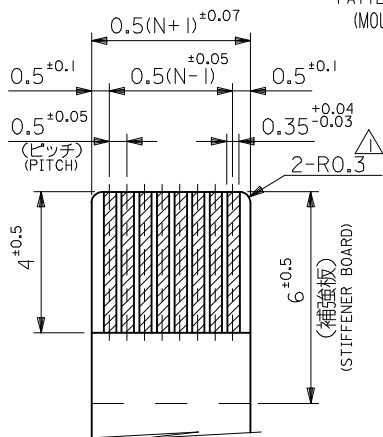
1. 使用材料 (MATERIAL)
 ターミナル (TERMINAL): リン青銅、ニッケル下地 金メッキ (接点部)、錫メッキ (テール部)
 (PHOSPHOR BRONZE t=0.2, GOLD (CONTACT), TIN (TAIL) PLATING OVER NICKEL)
 ハウジング (HOUSING): 46ナイロン(46NYLON), UL94V-0
 金具 (FITTING NAIL): リン青銅、ニッケル下地、錫メッキ
 (PHOSPHOR BRONZE t=0.2, TIN PLATING OVER NICKEL)
 △ パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB, PATTERN.)
 △ ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向 0.1MAX., 下方向 0.15MAX. とする。
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L .
 UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.
 △ 偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
 5. 本製品は 52689-**40 の鉛フリー (部分金メッキ) 品である。
 THIS PRODUCT IS LEAD FREE OF 52689-**40 (CONTACT GOLD PLATING).

REVISED EC NO: J2016-0905 DRWN: YMIZUNO02 2016/02/24 CHKD: TAKAHASHI 2016/02/29 APPR: KUSUHARA01 2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	± 0.03	DRAWN BY M. NABE I	DATE '04/08/06	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-	
	0.25 OVER	0.5 UNDER	± 0.05	CHECKED BY K. TOJO	DATE '04/08/06		
	0.5 OVER	1.0 UNDER	± 0.1	APPROVED BY N. UKITA	DATE '04/08/06		
1.0 OVER	10 UNDER	± 0.2	MATERIAL NO. SEE SHEET 2		DOCUMENT NO. SD-52689-040	SHEET NO. 1 OF 2	
10 OVER	30 UNDER	± 0.25	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
30 OVER		± 0.3	ANGULAR ±3 °				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							



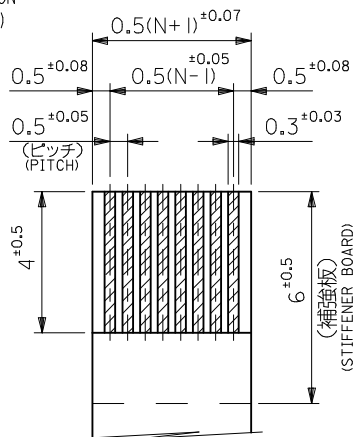
参考基板レイアウト
(マウント面)

REFERENCE P.C. BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合 FPC 推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合 FFC 推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

注記 NOTES

△ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

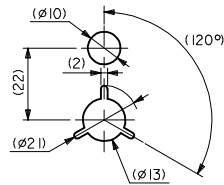
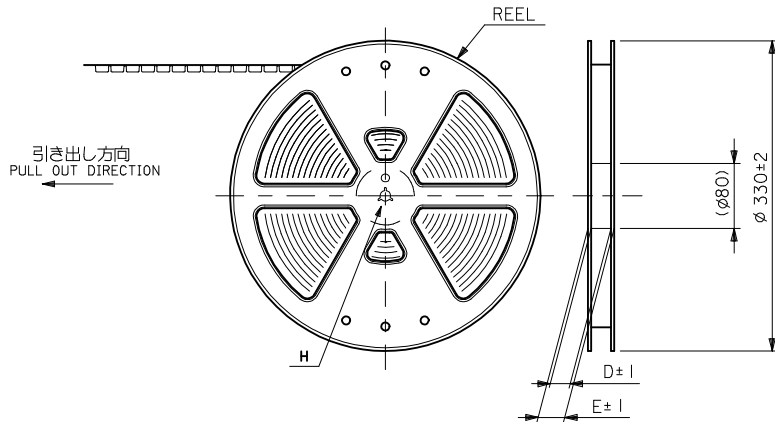
ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

52689-**-66	17.6	21.1	19.3	15.5	14.5	52689-3075	52689-3066	30
	14.6	18.1	16.3	12.5	11.5	52689-2475	52689-2466	24
	13.1	16.6	14.8	11.0	10.0	52689-2175	52689-2166	21
MODEL NO.	W	D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	極数 CKT.
	ORDER No. オーダー番号							

REVISED EC NO: J2016-0905 DRWN: YIMZUN02 2016/02/24 CHKD: TAKAHASHI 2016/02/29 APPR: KUSUHARA01 2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	0.25 UNDER	UNDER	±0.03	DRAWN BY MNABEI	DATE '04/08/06	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-		
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY KTOJO	DATE '04/08/06			
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY NUKITA	DATE '04/08/06			
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
10 OVER	30 UNDER	±0.25	SEE TABLE		SD-52689-040	2 OF 2		
30 OVER		±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
ANGULAR	±3 °							
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								

注記 NOTES

- 製品詳細寸法については図面 SD-52689-040 を参照下さい。
RE DETAILED DIMENSION,SEE SD-52689-040.
- 梱包数量：1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



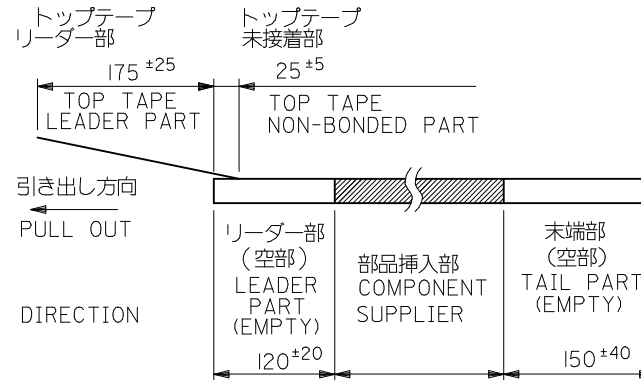
DETAIL H

5. 材料 キャリアテープ：ポリプロピレン (PP)
 トップテープ：PET, PE, PEF
 リール：ポリスチレン (PS)

MATERIAL CARRIER TAPE:POLYPROPYLENE
 TOP TAPE:PET,PE,PEF
 REEL:POLYSTYRENE

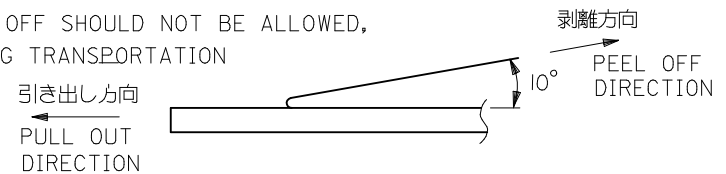
6. 本製品は 52689-**97 の鉛フリー(部分金メッキ)品である。
 THIS PRODUCT IS LEAD FREE OF 52689-**97 (CONTACT GOLD PLATING).

7. 本製品は乾燥剤入り、ハイバリア梱包仕様である。
 THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

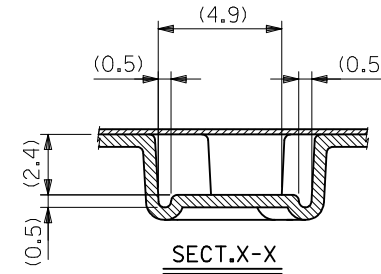
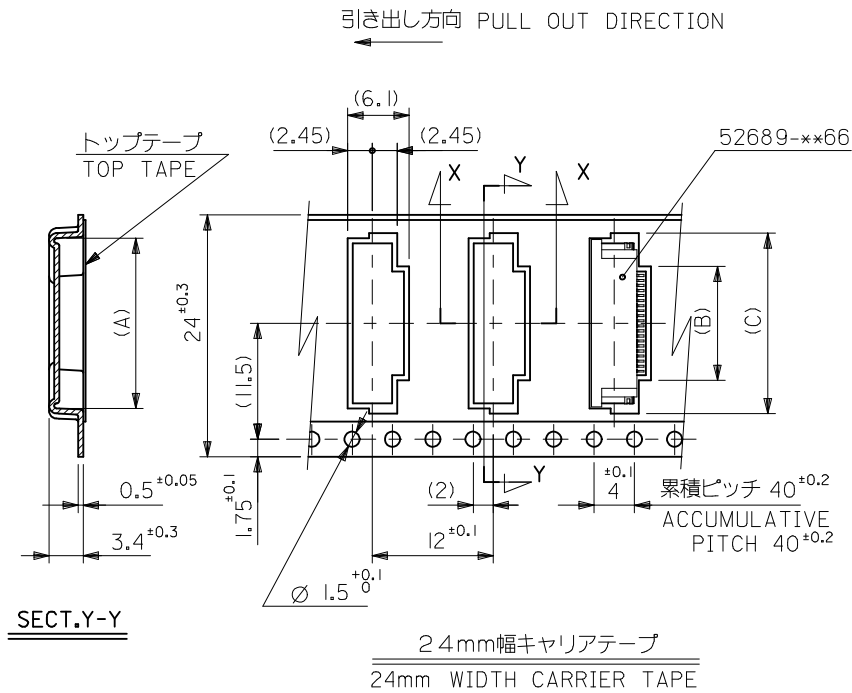


- トップテープの剥離強度：(剥離方向は下図参照)
 0.1~1.3N {10~130gf} 尚、本規格値は、出荷時に適用。
 (但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE
 0.1~1.3N {10~130gf}(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
 PEEL OFF SHOULD NOT BE ALLOWED,
 DURING TRANSPORTATION

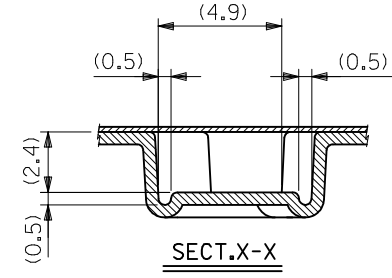
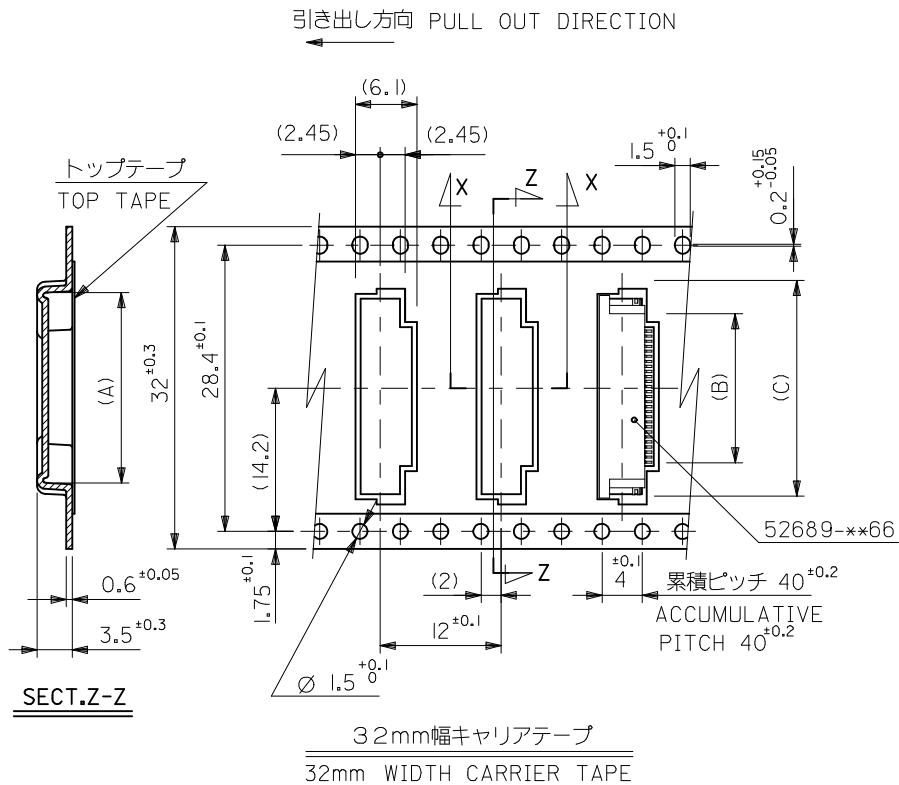


REVISED EC NO: J2016-0905 DRWN:YMIZUNO02 2016/02/24 CHKD:KATAHASHI 2016/02/29 APPR:IKUSUHARA01 2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	52689-**75	MODEL NO.
	0.25 UNDER	UNDER	±0.03	DRAWN BY MNABEI	DATE '04/08/06	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY KTOJO	DATE '04/08/06	EMBOSSD TAPE PACKAGE FOR 52689-**66 -LEAD FREE-	
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY NUKITA	DATE '04/08/06	molex	
1.0 OVER	30 UNDER	±---	MATERIAL NO.	DOCUMENT NO.	SEE TABLE	SD-52689-041	SHEET NO. 1 OF 3
30 OVER		±---	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
ANGULAR	±--- °						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							



24	29.4	25.4	17.9	11.3	16.9	52689-2175	21
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MAIERIAL NO.	CIRCUIT

REVISED EC NO: J2016-0905 DRWN: YMIZUNO02 2016/02/24 CHKD: KTAHAKASHI 2016/02/29 APPR: IKUSUHARA01 2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	0.25 UNDER UNDER ±0.03		MM ONLY		---	METRIC	☉
	0.25 OVER 0.5 UNDER ±0.05		DRAWN BY DATE		TITLE		
	0.5 OVER 1.0 UNDER ±0.1		MNABEI '04/08/06		EMBOSSD TAPE PACKAGE		
	1.0 OVER 10 UNDER ±---		CHECKED BY DATE		FOR 52689-**66		
10 OVER 30 UNDER ±---		KTOJO '04/08/06		-LEAD FREE-			
30 OVER ±---		APPROVED BY DATE		molex			
ANGULAR ±--- °		NUKITA '04/08/06		DOCUMENT NO.		SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-52689-041		2 OF 3	
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



32	37.4	33.4	22.4	15.8	21.4	52689-3075	30
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	52689-2475	24
						MATERIAL NO.	CIRCUIT

REVISED EC NO: J2016-0905 DRWN: YIMZUN02 2016/02/24 CHKD: TAKAHASHI 2016/02/29 APPR: KUSUHARA01 2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	0.25 UNDER UNDER ±0.03		MM ONLY		---	METRIC	☉	
	0.25 OVER 0.5 UNDER ±0.05		DRAWN BY		DATE			TITLE
	0.5 OVER 1.0 UNDER ±0.1		MNABEI		'04/08/06			EMBOSSED TAPE PACKAGE FOR 52689-**66 -LEAD FREE- molex
	1.0 OVER 10 UNDER ±---		CHECKED BY		DATE			
10 OVER 30 UNDER ±---		KTOJO		'04/08/06			MATERIAL NO. DOCUMENT NO. SHEET NO. SEE TABLE SD-52689-041 3 OF 3	
30 OVER ±---		APPROVED BY		DATE				
ANGULAR ±--- °		NUKITA		'04/08/06				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
		A3						